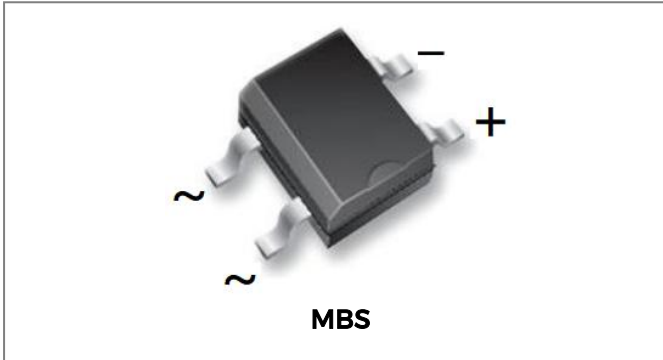


MB05S THRU MB10S

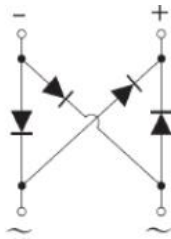
Single-Phase 0.8A Surface Mount Glass Passivated Bridge Rectifier



Features

- Glass passivated die construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-30A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0
- Terminals finish: 100% Pure Tin
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: Reliable low cost construction utilizing molded plastic technique
- Terminals: Plated Leads Solderable per MIL STD-202, Method 208
- Polarity: As Marked on Case
- Mounting Position: Any

Maximum Ratings @T_A=25°C unless otherwise specified

Type Number	Symbol	MB05S	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Units
Peak Repetitive Reverse Voltage DC Blocking Voltage	V_{RRM} V_{DC}	50	100	200	400	600	800	1000	V
RMS Voltage	V_{RMS}	35	70	140	280	420	480	700	V
Average Rectified Output Current (Note1)@T _A =40°C (Note 2)@T _A =40°C	I_O	0.5 0.8							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A

Electrical Characteristics: @ $T_A=25^\circ\text{C}$ unless otherwise specified

Type Number	Symbol	MB05S	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Units
Forward Voltage per element @ $I_F=0.8\text{A}$	V_{FM}				1.1				V
Peak Reverse Current @ $T_A=25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$	I_R				5 500				μA
Typical Junction Capacitance (Note 3)	C_j				13				pF

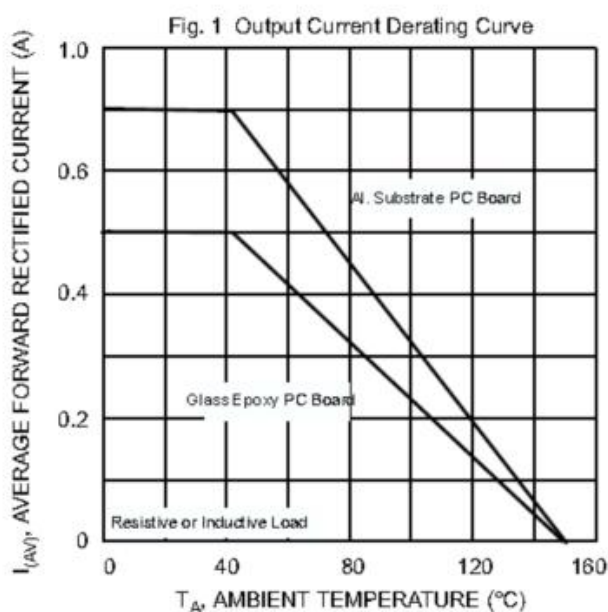
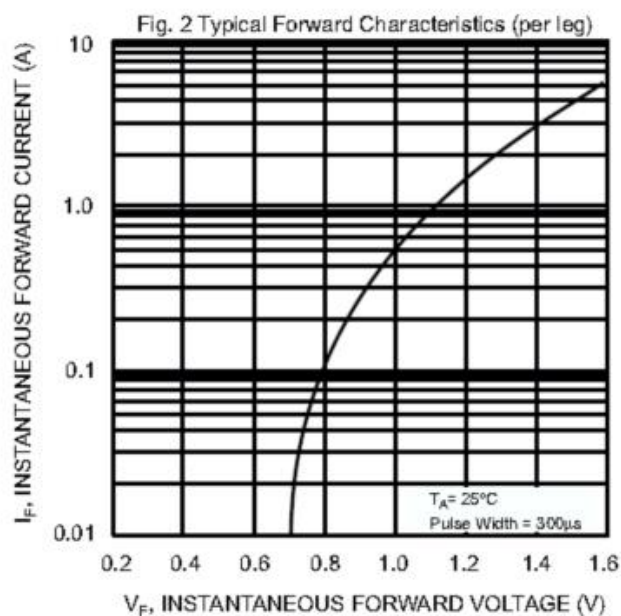
* Pulse width < 300 μs , duty cycle < 2%

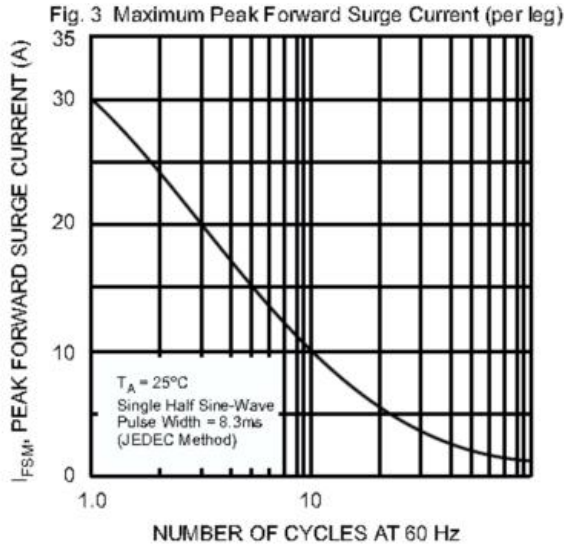
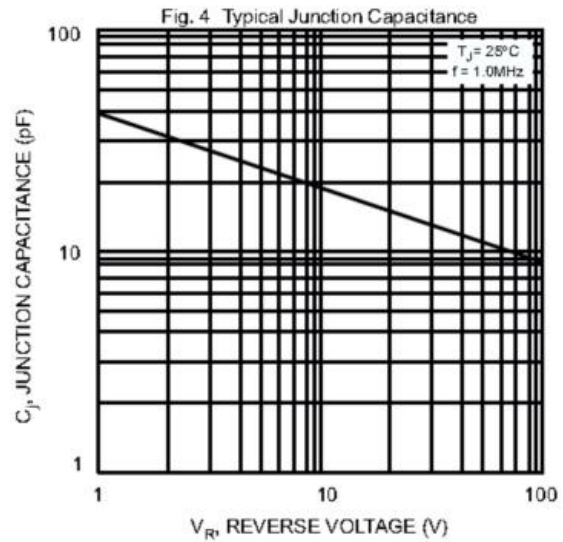
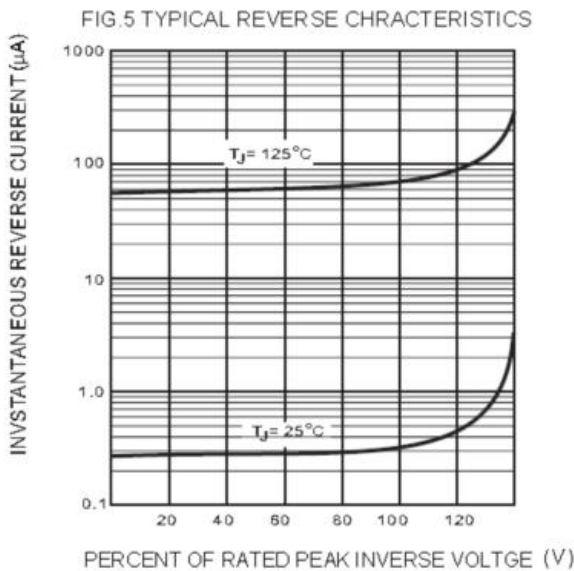
Thermal-Mechanical Specifications: @ $T_A=25^\circ\text{C}$ unless otherwise specified

Type Number	Symbol	MB05S	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Units
Typical Thermal Resistance per leg	$R_{\theta JA}$				70				$^\circ\text{C}/\text{W}$
	$R_{\theta JL}$				20				
Operating Junction and Storage Temperature Range	T_J, T_{STG}				-55+150				$^\circ\text{C}$

Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.
2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.
3. Measured at 1.0 MHz and applied reverse voltage of 4.0 VDC

Ratings and Characteristics Curves



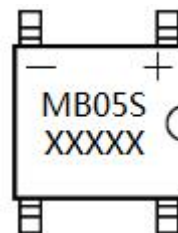


Ordering Information

Device	Package	Plating	Shipping
MB05S THRU MB10S	MBS (Pb-Free)	Pure Sn	3000pcs / reel
MB05S THRU MB10S	MBS (Pb-Free)	Pure Sn	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

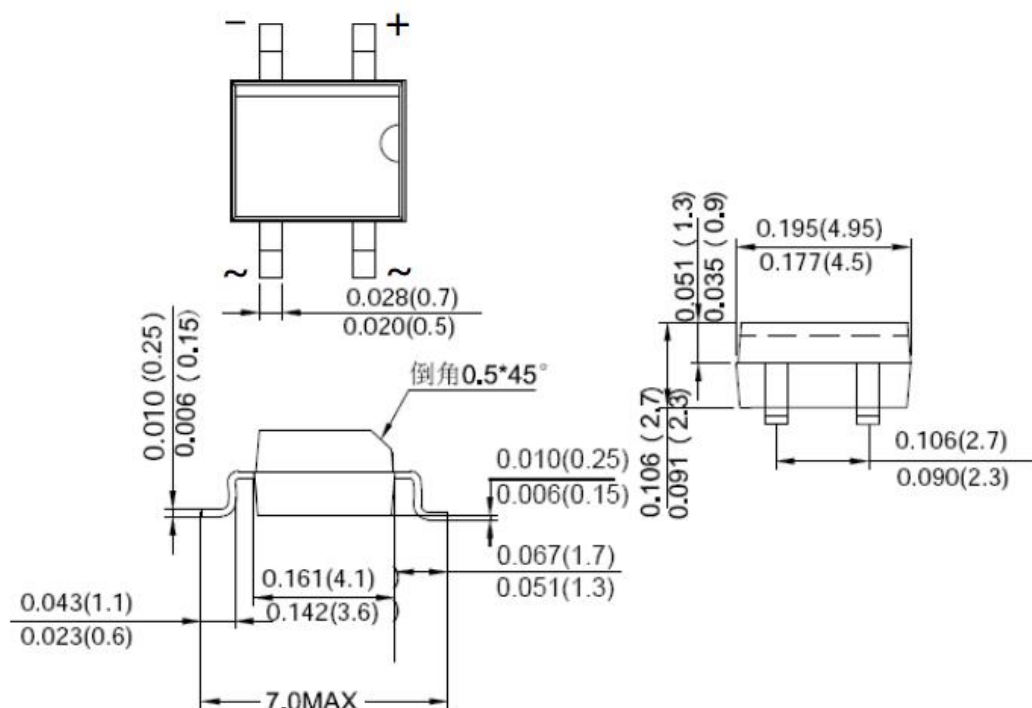


Where XXXXX is YYWWL

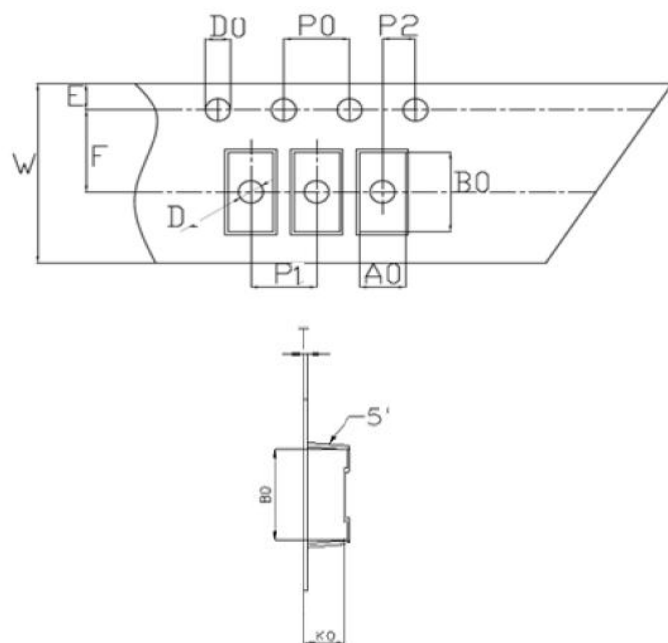
MB05S = Type Number
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL94V-0

Mechanical Dimensions MBS(Inches/Millimeters)



Carrier Tape Specification MBS



SYMBOL	Millimeters	
	Min.	Max.
A0	4.92	5.12
B0	7.12	7.32
D0	1.50	1.60
D1	1.40	1.60
P0	3.90	4.10
P1	7.90	8.10
P2	1.95	2.05
E	1.65	1.85
K0	2.78	2.98
F	5.45	5.55
W	11.90	12.10
T	0.24	0.30
10P0	39.80	40.20
抗拉拉力	≥3KG	

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